

WAFER PROCESSING METHOD

ABSTRACT

A wafer processing method includes a first fixing step of making a first resin sheet conform to a circular recessed portion and a ring-shaped reinforcing portion of a wafer by fixing an undersurface of the wafer to the first resin sheet, after the first fixing step, a second fixing step of forming a cavity between the first resin sheet fixed to the circular recessed portion and a second resin sheet by fixing the second resin sheet to the first resin sheet fixed to the ring-shaped reinforcing portion, after the second fixing step, a holding step of holding the second resin sheet of the wafer on a chuck table, and a groove forming step of forming a separating groove for separating the circular recessed portion and the ring-shaped reinforcing portion from each other.

[FIG. 4B]